



# STD4NA40

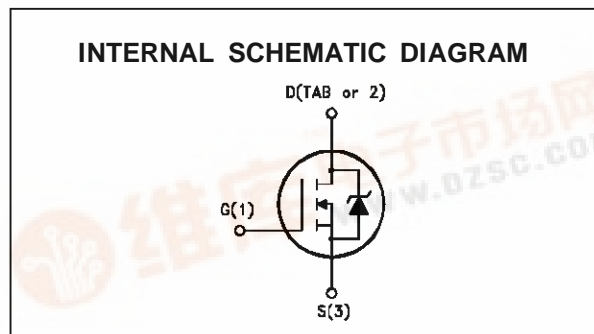
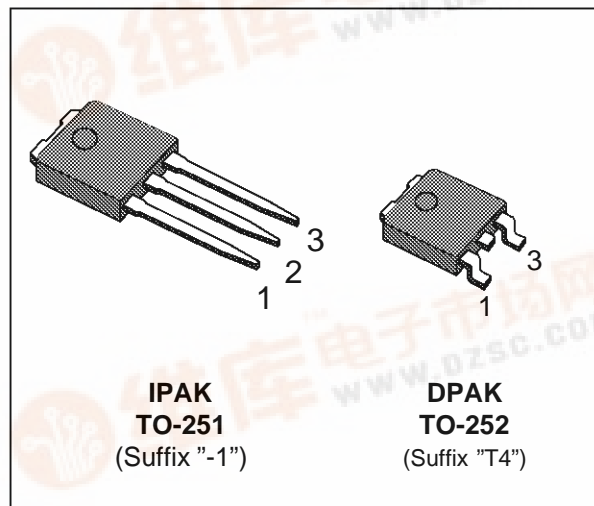
## N - CHANNEL ENHANCEMENT MODE FAST POWER MOS TRANSISTOR

| TYPE     | V <sub>DSS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> |
|----------|------------------|---------------------|----------------|
| STD4NA40 | 400 V            | < 2 Ω               | 3.3 A          |

- TYPICAL R<sub>DS(on)</sub> = 1.7 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- APPLICATION ORIENTED CHARACTERIZATION
- THROUGH-HOLE IPAK (TO-251) POWER PACKAGE IN TUBE (SUFFIX "-1")
- SURFACE-MOUNTING DPAK (TO-252) POWER PACKAGE IN TAPE & REEL (SUFFIX "T4")

### APPLICATIONS

- HIGH SPEED SWITCHING
- UNINTERRUPTIBLE POWER SUPPLY (UPS)
- MOTOR CONTROL, AUDIO AMPLIFIERS
- INDUSTRIAL ACTUATORS
- DC-DC & DC-AC CONVERTERS FOR TELECOM, INDUSTRIAL AND CONSUMER ENVIRONMENT
- PARTICULARLY SUITABLE FOR ELECTRONIC FLUORESCENT LAMP BALLASTS



### ABSOLUTE MAXIMUM RATINGS

| Symbol              | Parameter   | Value      | Unit |
|---------------------|---|------------|------|
| V <sub>DS</sub>     | Drain-source Voltage (V <sub>GS</sub> = 0)            | 400        | V    |
| V <sub>DGR</sub>    | Drain- gate Voltage (R <sub>GS</sub> = 20 kΩ)         | 400        | V    |
| V <sub>GS</sub>     | Gate-source Voltage                                   | ± 30       | V    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>c</sub> = 25 °C  | 3.3        | A    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>c</sub> = 100 °C | 2.1        | A    |
| I <sub>DM</sub> (•) | Drain Current (pulsed)                                | 13.2       | A    |
| P <sub>tot</sub>    | Total Dissipation at T <sub>c</sub> = 25 °C           | 50         | W    |
|                     | Derating Factor                                       | 0.4        | W/°C |
| T <sub>stg</sub>    | Storage Temperature                                   | -65 to 150 | °C   |
| T <sub>j</sub>      | Max. Operating Junction Temperature                   | 150        | °C   |

(•) Pulse width limited by safe operating area



## STD4NA40

### THERMAL DATA

|                |  |     |     |               |
|----------------|--|-----|-----|---------------|
| $R_{thj-case}$ | Thermal Resistance Junction-case               | Max | 2.5 | $^{\circ}C/W$ |
| $R_{thj-amb}$  | Thermal Resistance Junction-ambient            | Max | 100 | $^{\circ}C/W$ |
| $R_{thc-sink}$ | Thermal Resistance Case-sink                   | Typ | 1.5 | $^{\circ}C/W$ |
| $T_I$          | Maximum Lead Temperature For Soldering Purpose |     | 275 | $^{\circ}C$   |

### AVALANCHE CHARACTERISTICS

| Symbol   | Parameter   | Max Value | Unit |
|----------|---|-----------|------|
| $I_{AR}$ | Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by $T_j$ max, $\delta < 1\%$ )                         | 3.3       | A    |
| $E_{AS}$ | Single Pulse Avalanche Energy (starting $T_j = 25^{\circ}C$ , $I_D = I_{AR}$ , $V_{DD} = 50 V$ )                            | 60        | mJ   |
| $E_{AR}$ | Repetitive Avalanche Energy (pulse width limited by $T_j$ max, $\delta < 1\%$ )   | 2.5       | mJ   |
| $I_{AR}$ | Avalanche Current, Repetitive or Not-Repetitive ( $T_c = 100^{\circ}C$ , pulse width limited by $T_j$ max, $\delta < 1\%$ ) | 2.1       | A    |

### ELECTRICAL CHARACTERISTICS ( $T_{case} = 25^{\circ}C$ unless otherwise specified)

OFF

| Symbol        | Parameter  | Test Conditions  | Min. | Typ. | Max.      | Unit               |
|---------------|--|--|------|------|-----------|--------------------|
| $V_{(BR)DSS}$ | Drain-source Breakdown Voltage                   | $I_D = 250 \mu A$ $V_{GS} = 0$   | 400  |      |           | V                  |
| $I_{DSS}$     | Zero Gate Voltage Drain Current ( $V_{GS} = 0$ ) | $V_{DS} = \text{Max Rating}$<br>$V_{DS} = \text{Max Rating} \times 0.8$ $T_c = 125^{\circ}C$ |      |      | 25<br>250 | $\mu A$<br>$\mu A$ |
| $I_{GSS}$     | Gate-body Leakage Current ( $V_{DS} = 0$ )       | $V_{GS} = \pm 20 V$  |      |      | $\pm 100$ | nA                 |

ON (\*)

| Symbol       | Parameter                         | Test Conditions  | Min. | Typ. | Max. | Unit     |
|--------------|-----------------------------------|--|------|------|------|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage            | $V_{DS} = V_{GS}$ $I_D = 250 \mu A$                          | 2.25 | 3    | 3.75 | V        |
| $R_{DS(on)}$ | Static Drain-source On Resistance | $V_{GS} = 10V$ $I_D = 2 A$                                   |      | 1.7  | 2    | $\Omega$ |
| $I_{D(on)}$  | On State Drain Current            | $V_{DS} > I_{D(on)} \times R_{DS(on)max}$<br>$V_{GS} = 10 V$ | 4    |      |      | A        |

DYNAMIC

| Symbol       | Parameter                    | Test Conditions                                       | Min. | Typ. | Max. | Unit |
|--------------|------------------------------|---|------|------|------|------|
| $g_{fs} (*)$ | Forward Transconductance     | $V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 2 A$ | 1.0  | 2.5  |      | S    |
| $C_{iss}$    | Input Capacitance            | $V_{DS} = 25 V$ $f = 1 MHz$ $V_{GS} = 0$              |      | 375  | 490  | pF   |
| $C_{oss}$    | Output Capacitance           |   |      | 70   | 90   | pF   |
| $C_{rss}$    | Reverse Transfer Capacitance |   |      | 18   | 25   | pF   |

**ELECTRICAL CHARACTERISTICS** (continued)

**SWITCHING ON**

| Symbol         | Parameter             | Test Conditions   | Min. | Typ. | Max. | Unit             |
|----------------|-----------------------|---|------|------|------|------------------|
| $t_{d(on)}$    | Turn-on Time          | $V_{DD} = 200\text{ V}$ $I_D = 2\text{ A}$  |      | 13   | 20   | ns               |
| $t_r$          | Rise Time             | $R_G = 18\ \Omega$ $V_{GS} = 10\text{ V}$<br>(see test circuit, figure 3)   |      | 22   | 30   | ns               |
| $(di/dt)_{on}$ | Turn-on Current Slope | $V_{DD} = 320\text{ V}$ $I_D = 4\text{ A}$<br>$R_G = 18\ \Omega$ $V_{GS} = 10\text{ V}$<br>(see test circuit, figure 5) |      | 385  |      | A/ $\mu\text{s}$ |
| $Q_g$          | Total Gate Charge     | $V_{DD} = 320\text{ V}$ $I_D = 4\text{ A}$ $V_{GS} = 10\text{ V}$   |      | 20   | 28   | nC               |
| $Q_{gs}$       | Gate-Source Charge    |   |      | 5    |      | nC               |
| $Q_{gd}$       | Gate-Drain Charge     |   |      | 8    |      | nC               |

**SWITCHING OFF**

| Symbol        | Parameter             | Test Conditions                            | Min. | Typ. | Max. | Unit |
|---------------|-----------------------|--|------|------|------|------|
| $t_{r(Voff)}$ | Off-voltage Rise Time | $V_{DD} = 320\text{ V}$ $I_D = 4\text{ A}$ |      | 12   | 18   | ns   |
| $t_f$         | Fall Time             | $R_G = 18\ \Omega$ $V_{GS} = 10\text{ V}$  |      | 9    | 14   | ns   |
| $t_c$         | Cross-over Time       | (see test circuit, figure 5)               |      | 21   | 30   | ns   |

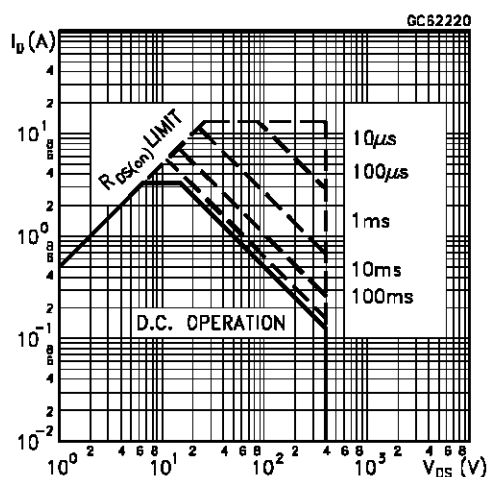
**SOURCE DRAIN DIODE**

| Symbol             | Parameter                     | Test Conditions   | Min. | Typ. | Max. | Unit          |
|--------------------|-------------------------------|---|------|------|------|---------------|
| $I_{SD}$           | Source-drain Current          |   |      |      | 4    | A             |
| $I_{SDM}(\bullet)$ | Source-drain Current (pulsed) |   |      |      | 16   | A             |
| $V_{SD}(\ast)$     | Forward On Voltage            | $I_{SD} = 4\text{ A}$ $V_{GS} = 0$  |      |      | 1.6  | V             |
| $t_{rr}$           | Reverse Recovery Time         | $I_{SD} = 4\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 100\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$<br>(see test circuit, figure 5) |      | 355  |      | ns            |
| $Q_{rr}$           | Reverse Recovery Charge       |   |      | 4.3  |      | $\mu\text{C}$ |
| $I_{RRM}$          | Reverse Recovery Current      |   |      | 24   |      | A             |

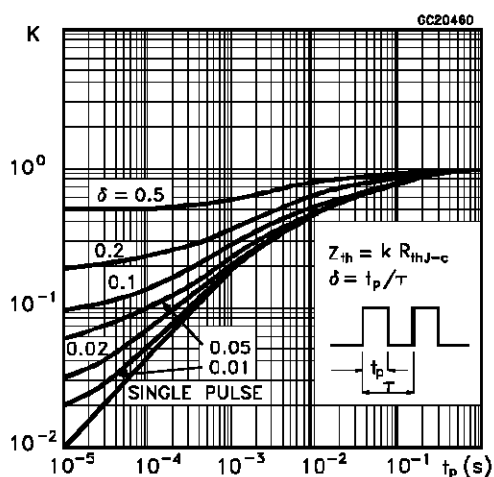
(\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %

(•) Pulse width limited by safe operating area

**Safe Operating Area**

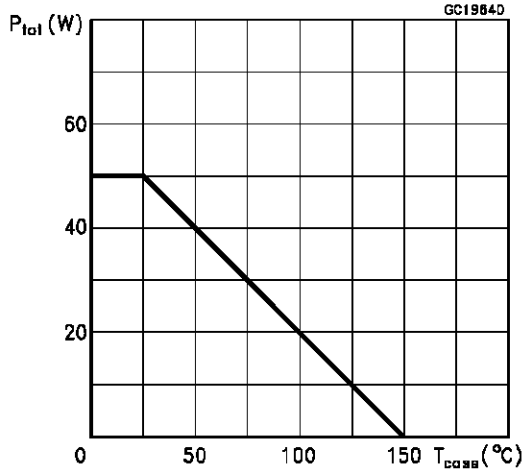


**Thermal Impedance**

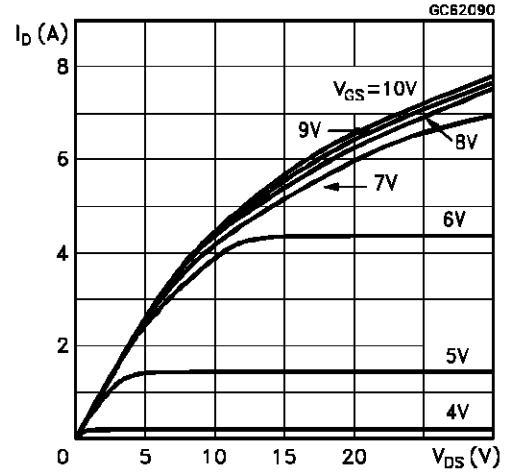


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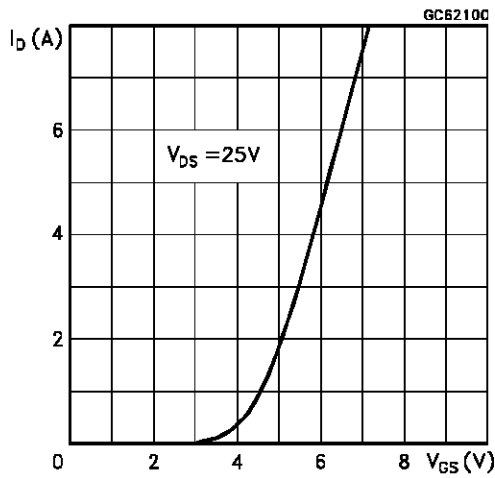
Derating Curve



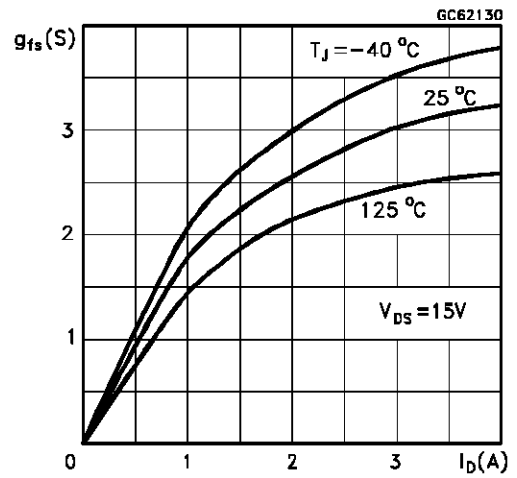
Output Characteristics



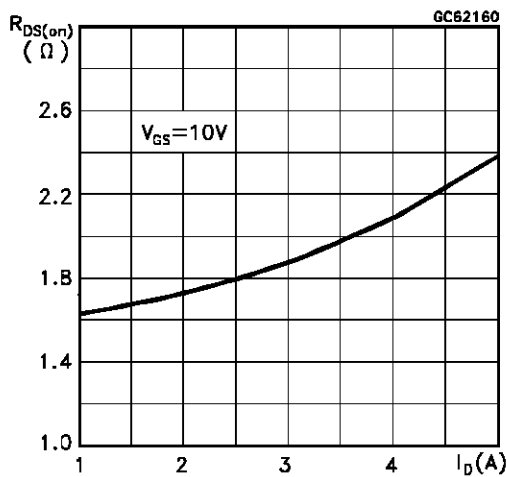
Transfer Characteristics



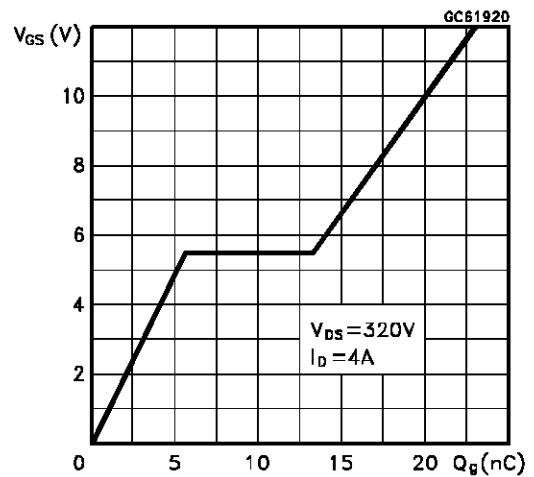
Transconductance



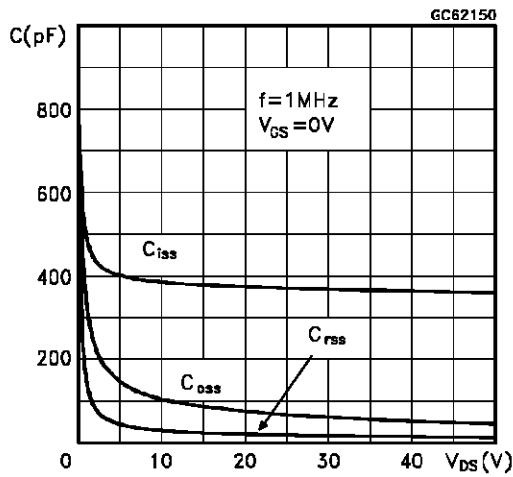
Static Drain-source On Resistance



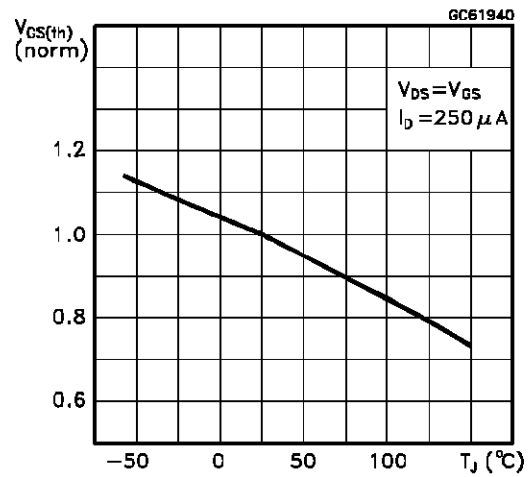
Gate Charge vs Gate-source Voltage



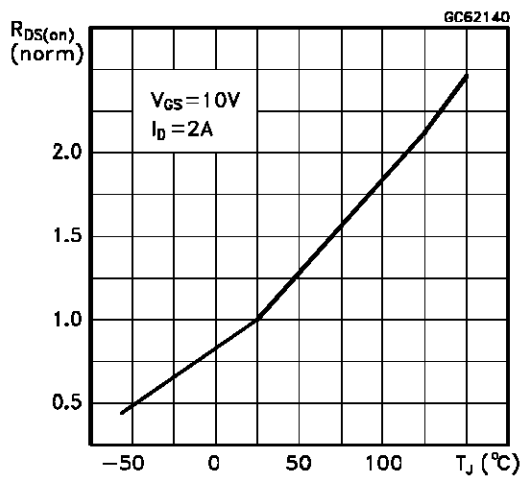
Capacitance Variations



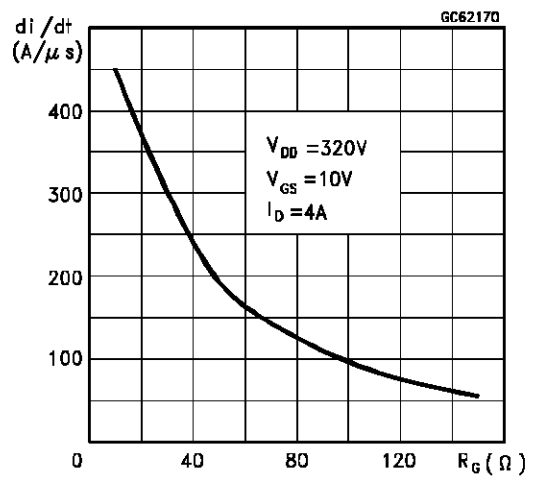
Normalized Gate Threshold Voltage vs Temperature



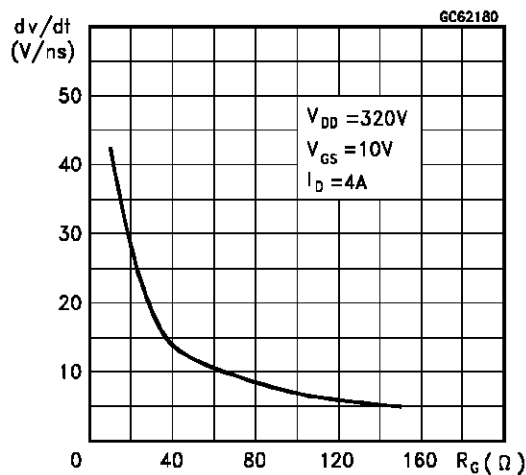
Normalized On Resistance vs Temperature



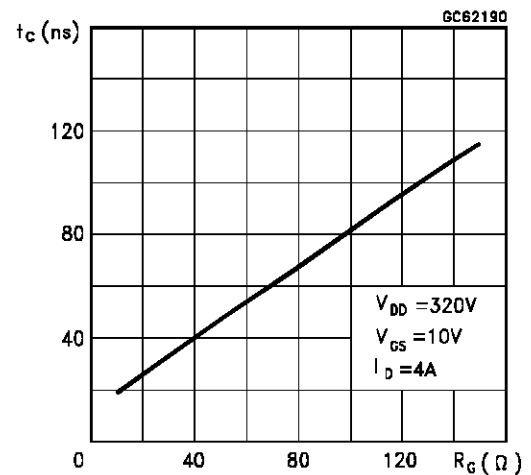
Turn-on Current Slope



Turn-off Drain-source Voltage Slope

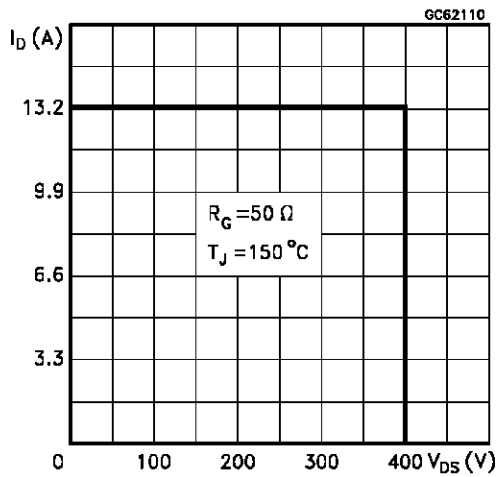


Cross-over Time

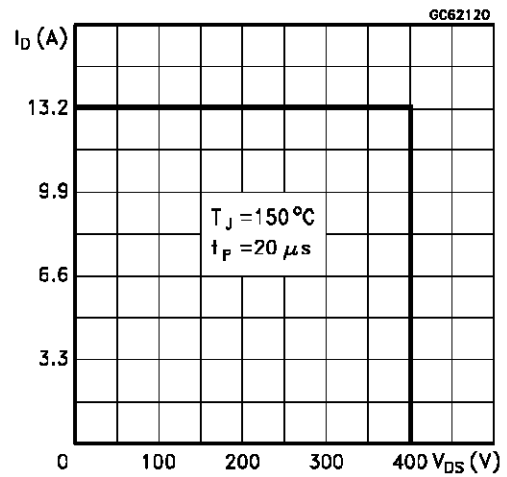


# STD4NA40

Switching Safe Operating Area



Accidental Overload Area



Source-drain Diode Forward Characteristics

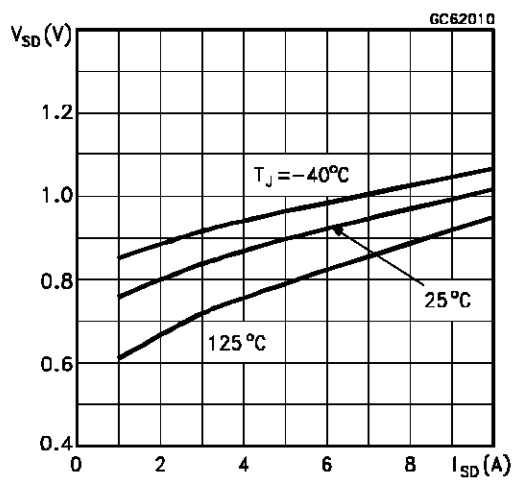
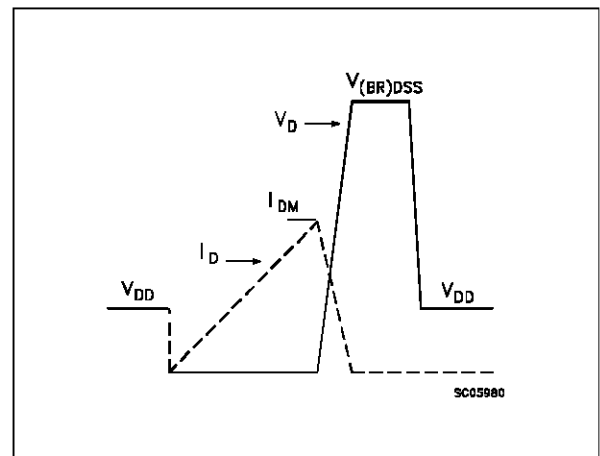
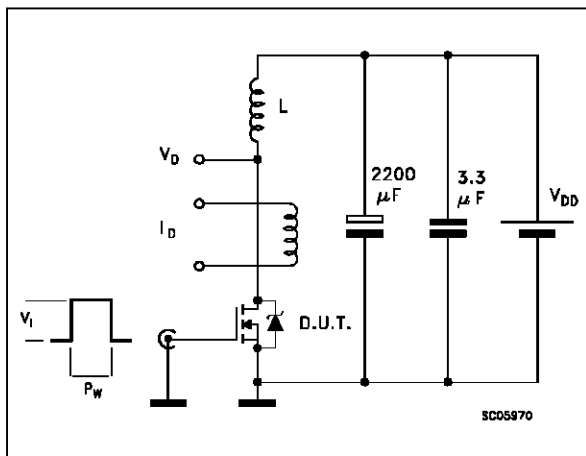
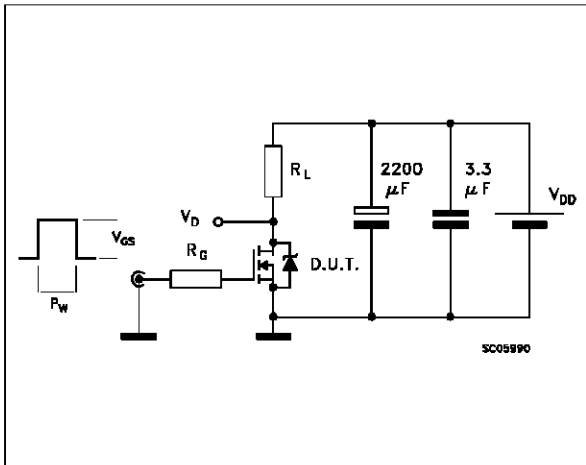


Fig. 1: Unclamped Inductive Load Test Circuits

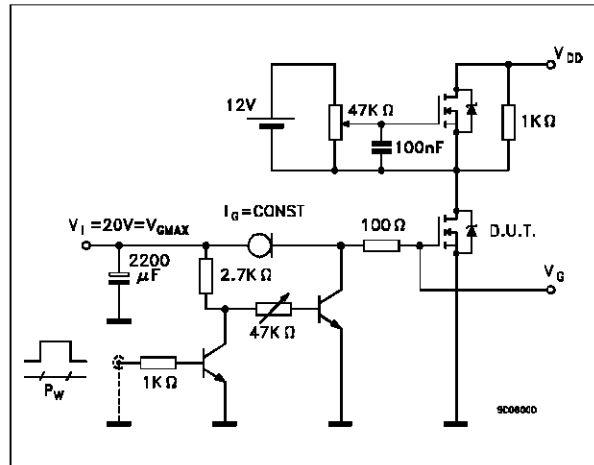
Fig. 2: Unclamped Inductive Waveforms



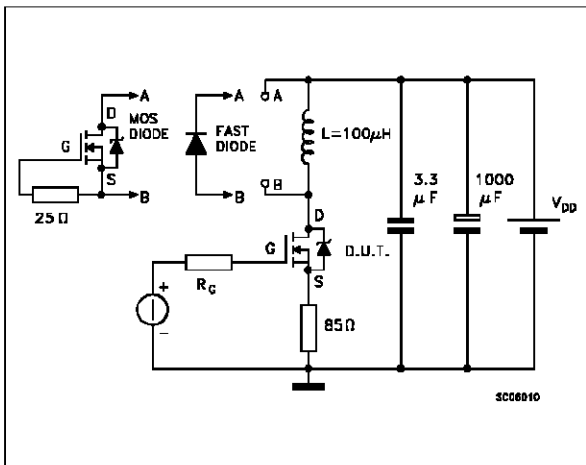
**Fig. 3:** Switching Times Test Circuits For Resistive Load



**Fig. 4:** Gate Charge Test Circuit

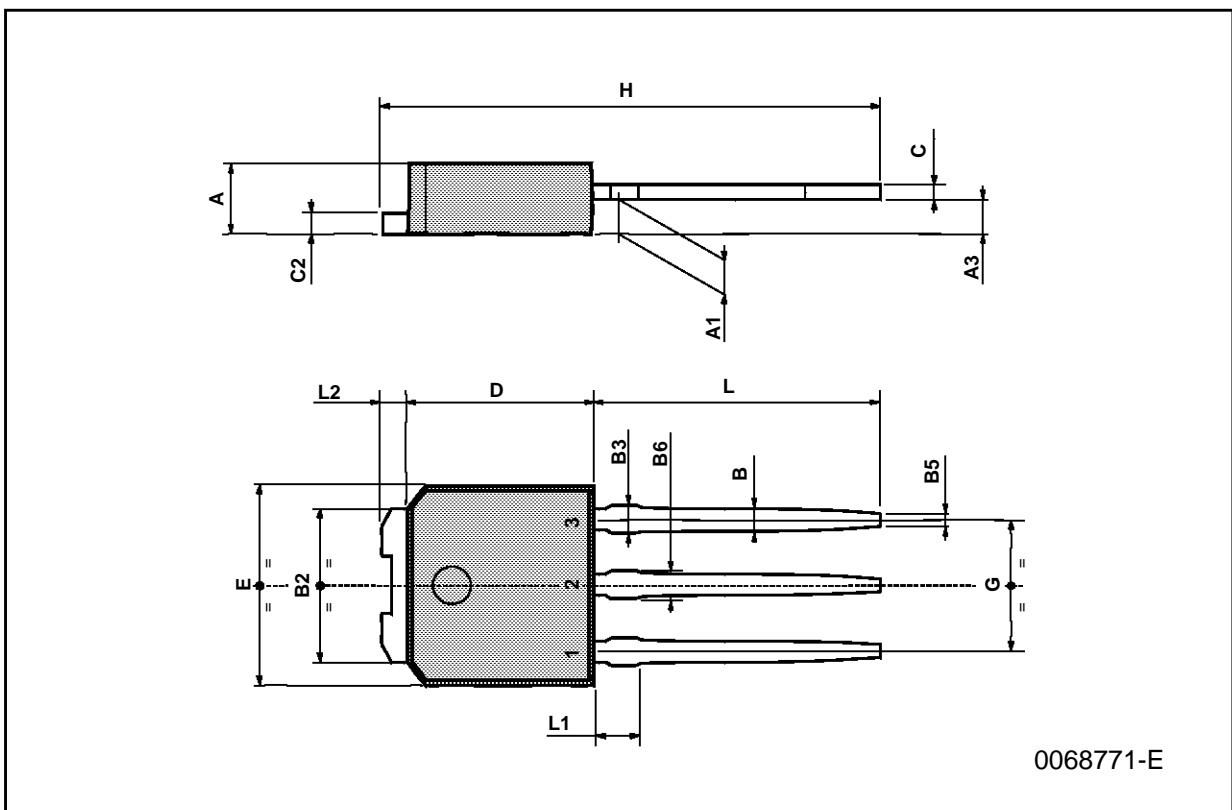


**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



**TO-251 (IPAK) MECHANICAL DATA**

| DIM. | mm   |      |      | inch  |       |       |
|------|------|------|------|-------|-------|-------|
|      | MIN. | TYP. | MAX. | MIN.  | TYP.  | MAX.  |
| A    | 2.2  |      | 2.4  | 0.086 |       | 0.094 |
| A1   | 0.9  |      | 1.1  | 0.035 |       | 0.043 |
| A3   | 0.7  |      | 1.3  | 0.027 |       | 0.051 |
| B    | 0.64 |      | 0.9  | 0.025 |       | 0.031 |
| B2   | 5.2  |      | 5.4  | 0.204 |       | 0.212 |
| B3   |      |      | 0.85 |       |       | 0.033 |
| B5   |      | 0.3  |      |       | 0.012 |       |
| B6   |      |      | 0.95 |       |       | 0.037 |
| C    | 0.45 |      | 0.6  | 0.017 |       | 0.023 |
| C2   | 0.48 |      | 0.6  | 0.019 |       | 0.023 |
| D    | 6    |      | 6.2  | 0.236 |       | 0.244 |
| E    | 6.4  |      | 6.6  | 0.252 |       | 0.260 |
| G    | 4.4  |      | 4.6  | 0.173 |       | 0.181 |
| H    | 15.9 |      | 16.3 | 0.626 |       | 0.641 |
| L    | 9    |      | 9.4  | 0.354 |       | 0.370 |
| L1   | 0.8  |      | 1.2  | 0.031 |       | 0.047 |
| L2   |      | 0.8  | 1    |       | 0.031 | 0.039 |

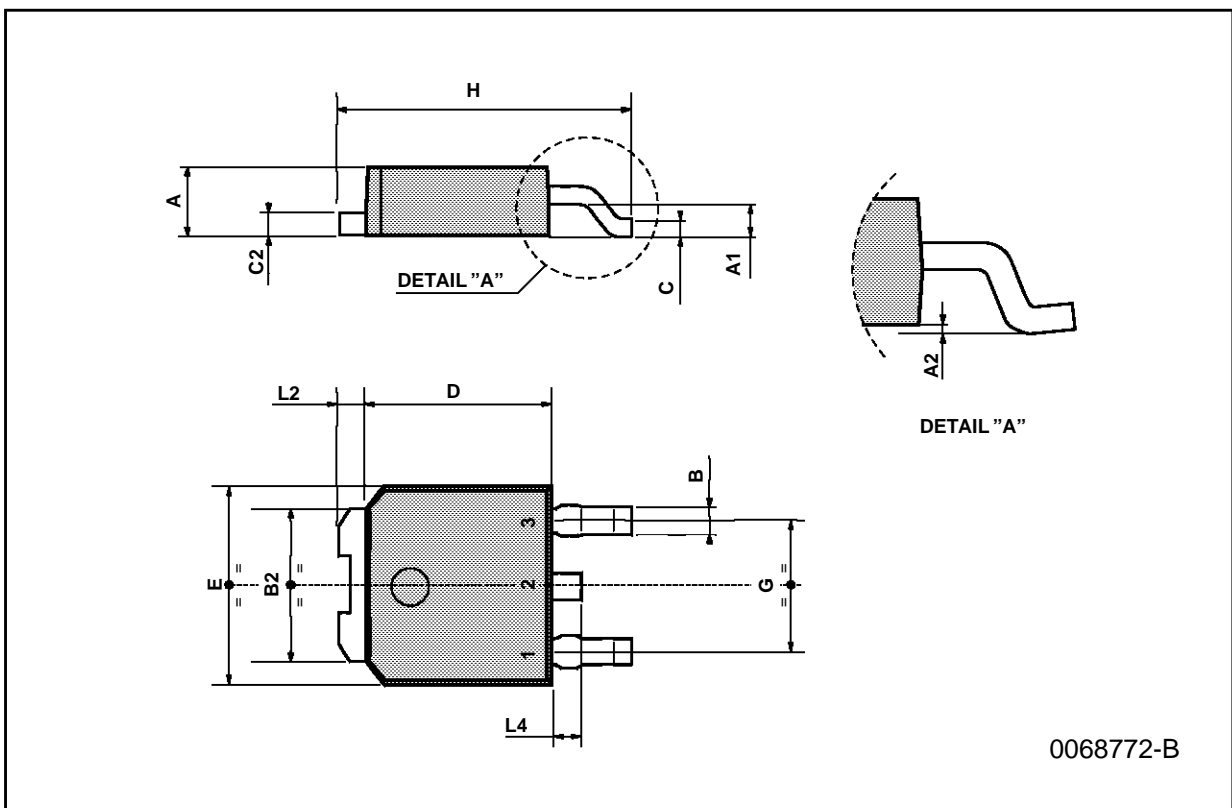


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**TO-252 (DPAK) MECHANICAL DATA**

| DIM. | mm   |      |      | inch  |       |       |
|------|------|------|------|-------|-------|-------|
|      | MIN. | TYP. | MAX. | MIN.  | TYP.  | MAX.  |
| A    | 2.2  |      | 2.4  | 0.086 |       | 0.094 |
| A1   | 0.9  |      | 1.1  | 0.035 |       | 0.043 |
| A2   | 0.03 |      | 0.23 | 0.001 |       | 0.009 |
| B    | 0.64 |      | 0.9  | 0.025 |       | 0.035 |
| B2   | 5.2  |      | 5.4  | 0.204 |       | 0.212 |
| C    | 0.45 |      | 0.6  | 0.017 |       | 0.023 |
| C2   | 0.48 |      | 0.6  | 0.019 |       | 0.023 |
| D    | 6    |      | 6.2  | 0.236 |       | 0.244 |
| E    | 6.4  |      | 6.6  | 0.252 |       | 0.260 |
| G    | 4.4  |      | 4.6  | 0.173 |       | 0.181 |
| H    | 9.35 |      | 10.1 | 0.368 |       | 0.397 |
| L2   |      | 0.8  |      |       | 0.031 |       |
| L4   | 0.6  |      | 1    | 0.023 |       | 0.039 |



## STD4NA40

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